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(12) **United States Design Patent** (10) **Patent No.:** **US D766,850 S**
Morisaki et al. (45) **Date of Patent:** **** Sep. 20, 2016**

(54) **WAFER HOLDER FOR MANUFACTURING SEMICONDUCTOR**

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(52) **U.S. Cl.**
USPC **D13/182**

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 211/41.18; 432/253, 258; 156/345.51,
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 CPC C23C 16/458; C23C 16/4581; C23C
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 C23C 16/4586; C23C 16/4587; C23C
 16/4588; C30B 31/14; H01L 21/673; H01L
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 H01L 21/67313; H01L 21/67316; H01L
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See application file for complete search history.

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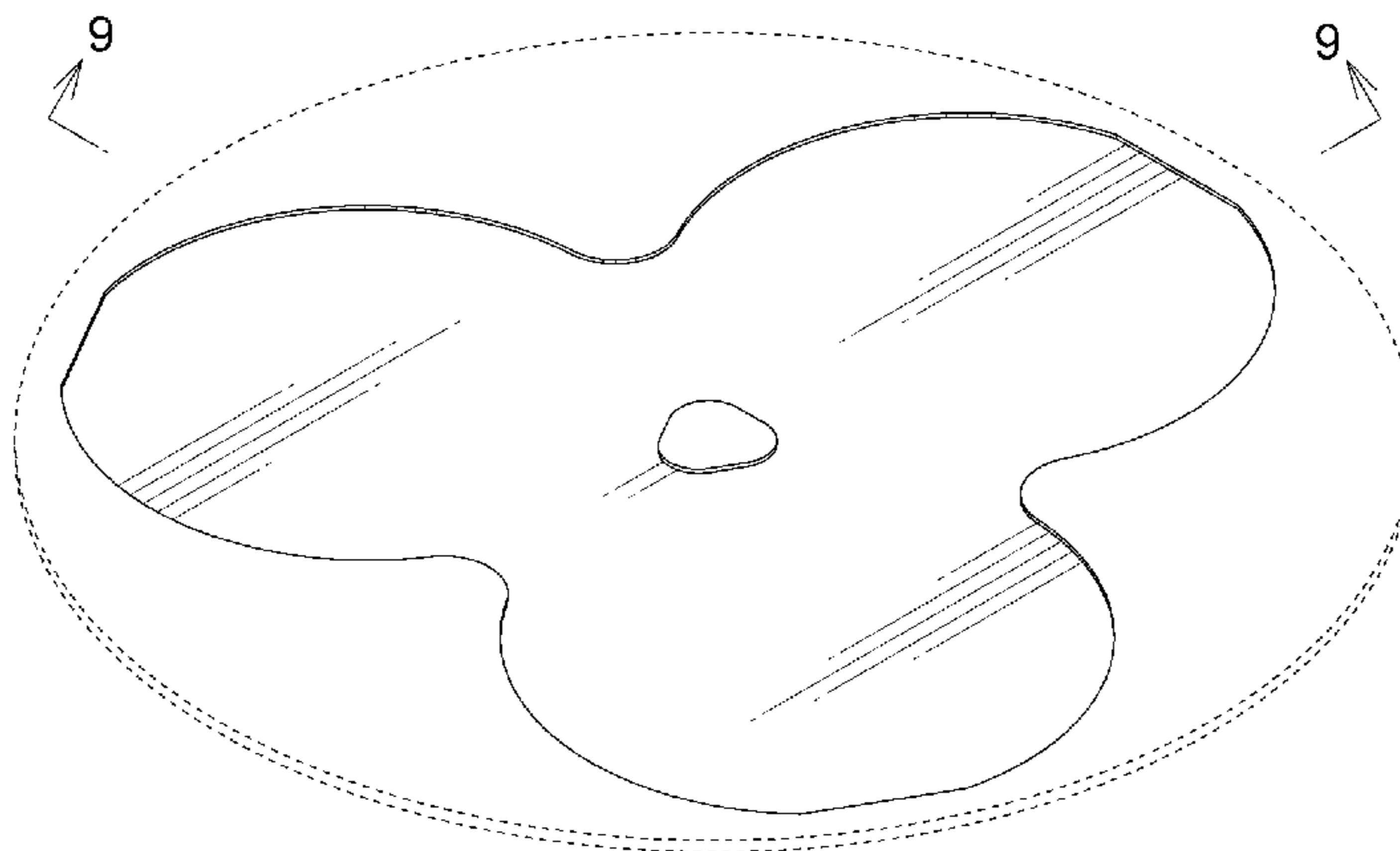
(57) **CLAIM**

The ornamental design for a wafer holder for manufacturing semiconductor, as shown and described.

DESCRIPTION

FIG. 1 is a front view of a wafer holder for manufacturing semiconductor showing our new design;
 FIG. 2 is a rear view thereof;
 FIG. 3 is a top plan view thereof;
 FIG. 4 is a bottom plan view thereof;
 FIG. 5 is a right side view thereof;
 FIG. 6 is a left side view thereof;
 FIG. 7 is a front perspective view thereof;
 FIG. 8 is an enlarged cross sectional view taken along line 8-8 in FIG. 1;
 FIG. 9 is an enlarged portion view taken along line 9-9 in FIG. 1; and,
 FIG. 10 is another front perspective view of FIG. 1 shown in a used condition with wafers shown in broken lines.
 The features shown in dotted lines depict environmental subject matter only and form no part of the claimed design.

1 Claim, 10 Drawing Sheets



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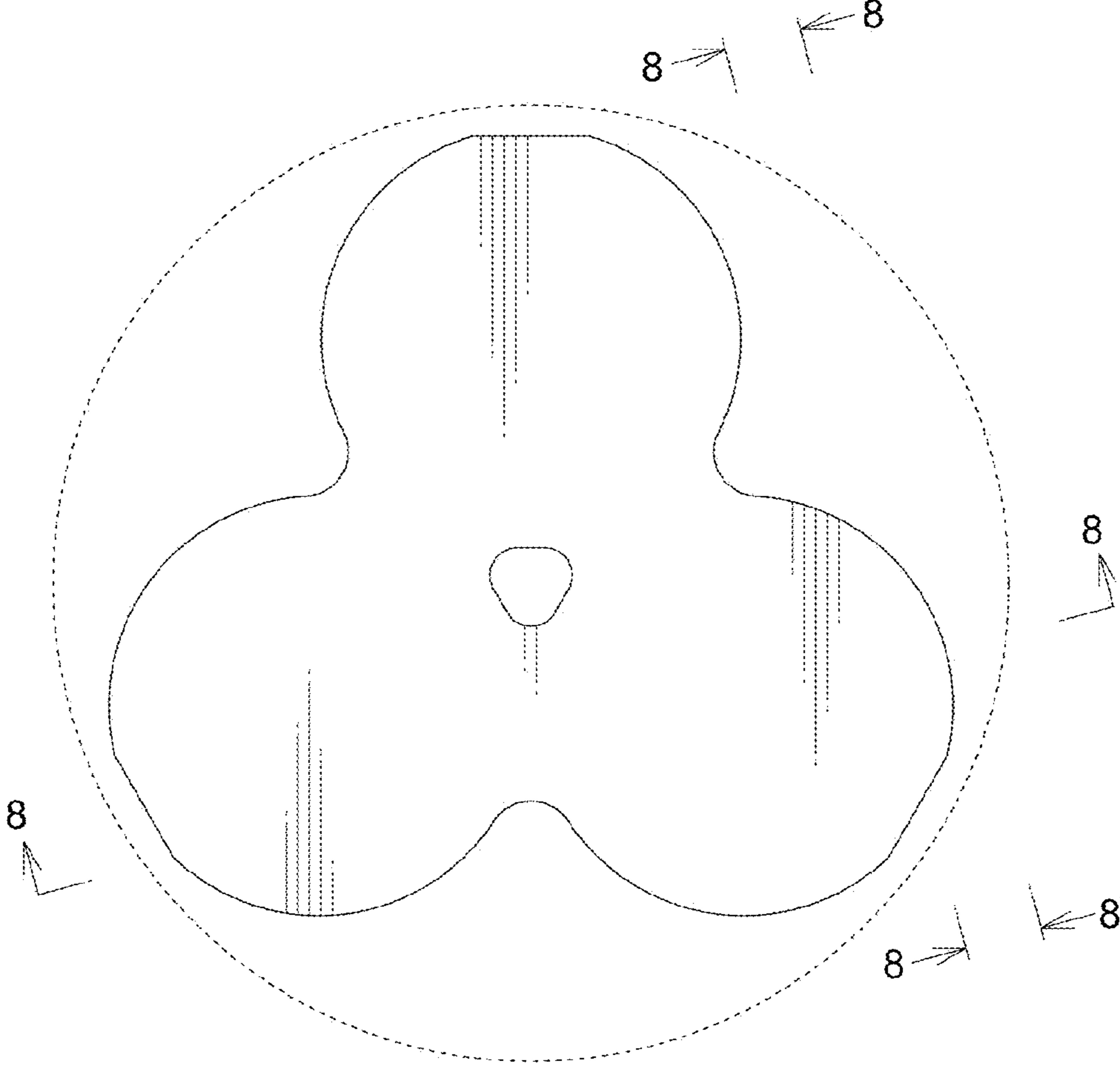


FIG. 1

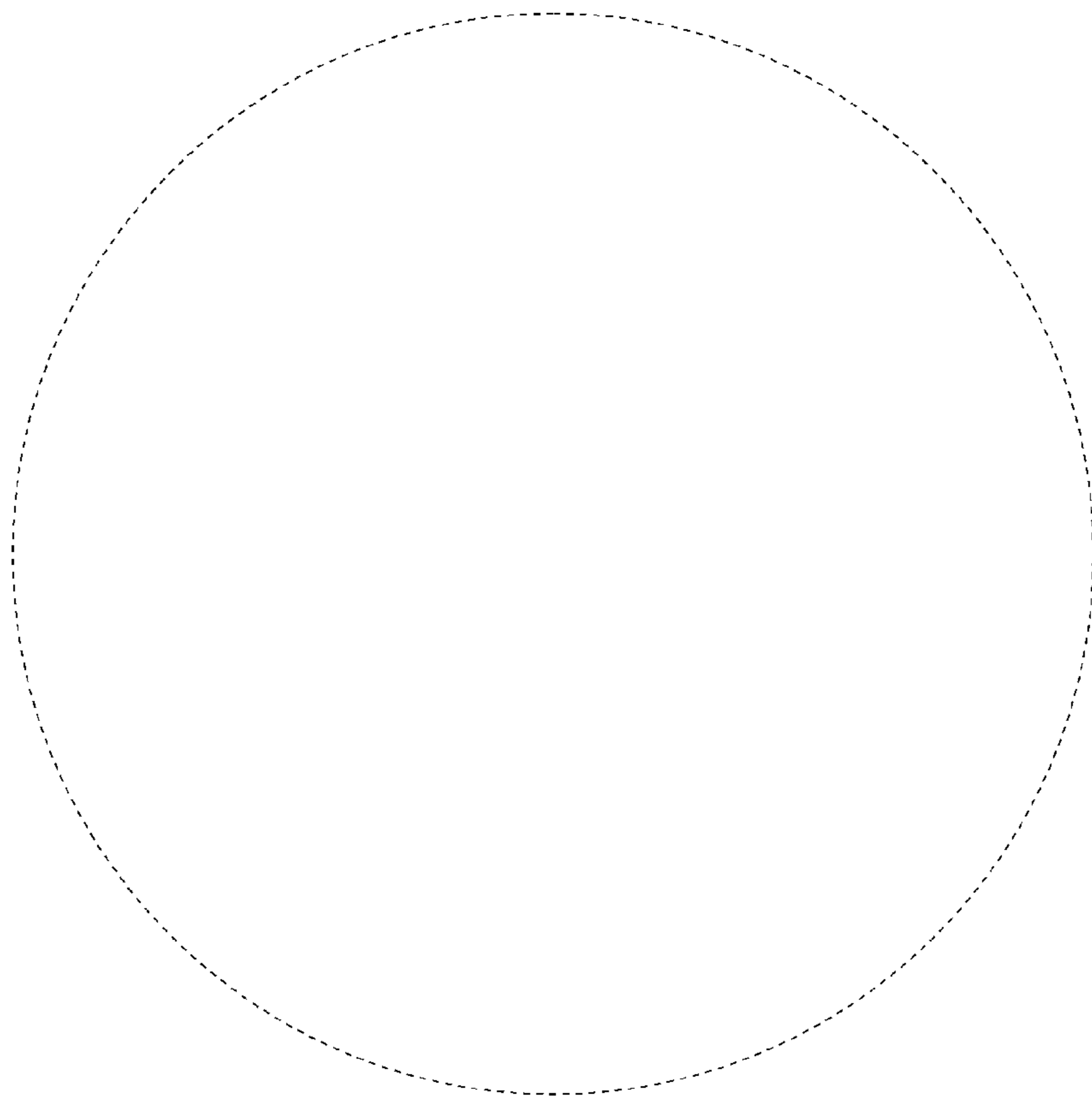


FIG. 2

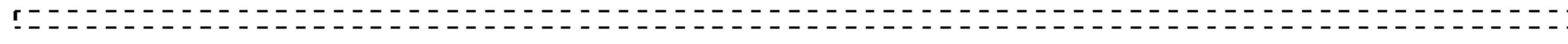


FIG. 3

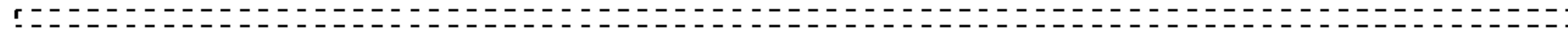


FIG. 4



FIG. 5



FIG. 6

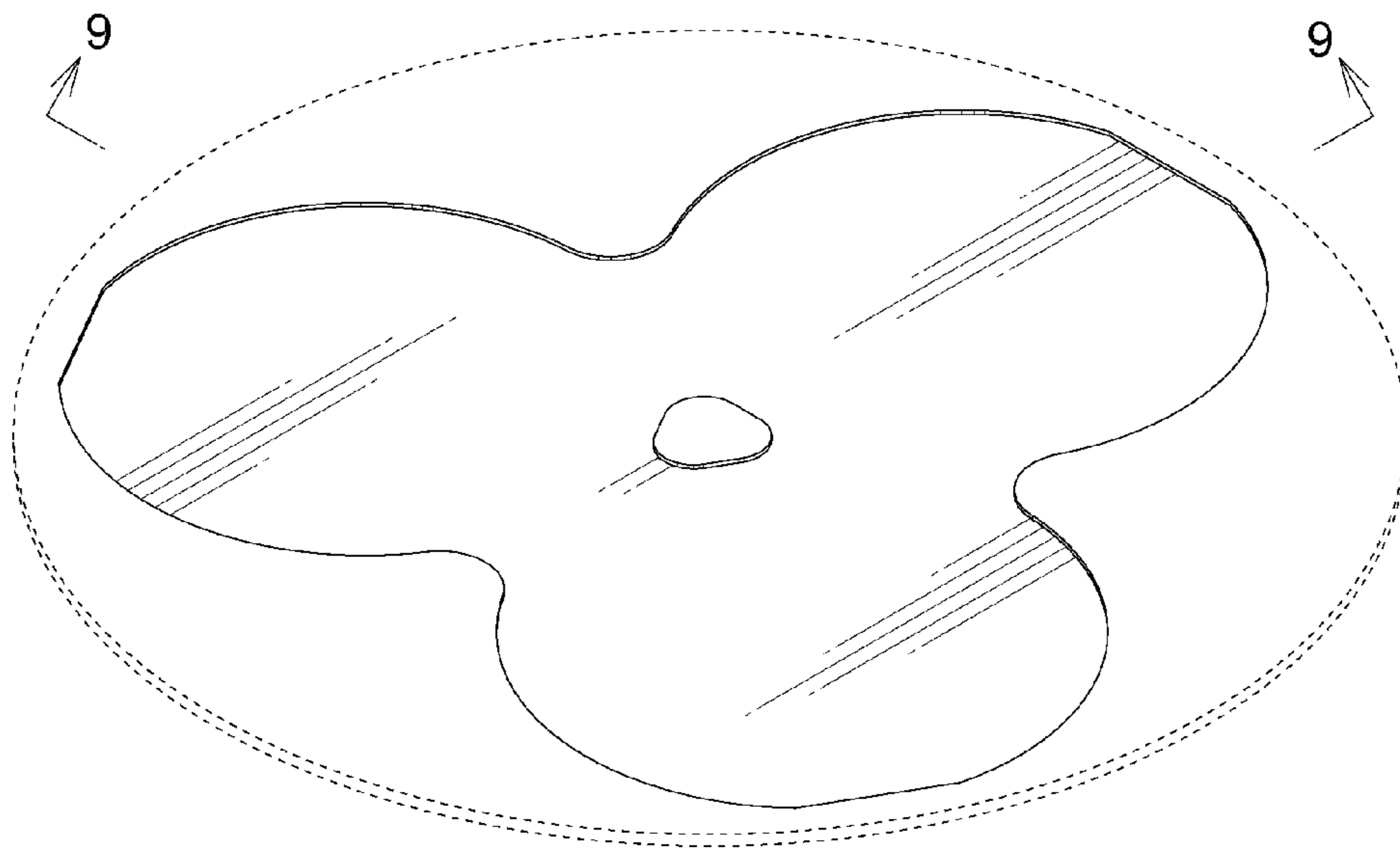


FIG. 7

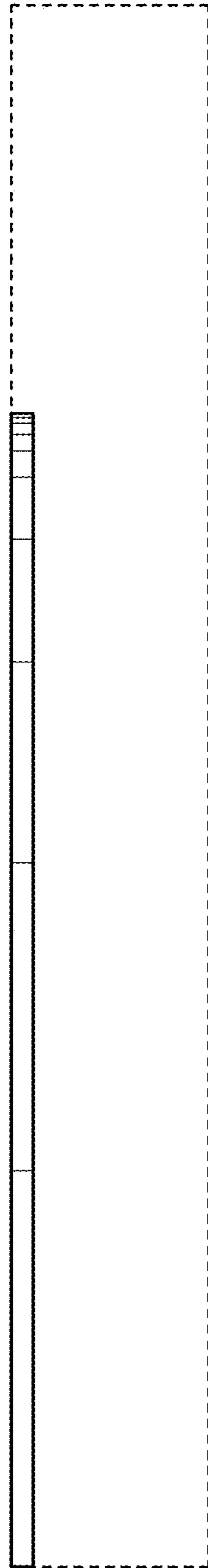


FIG. 8

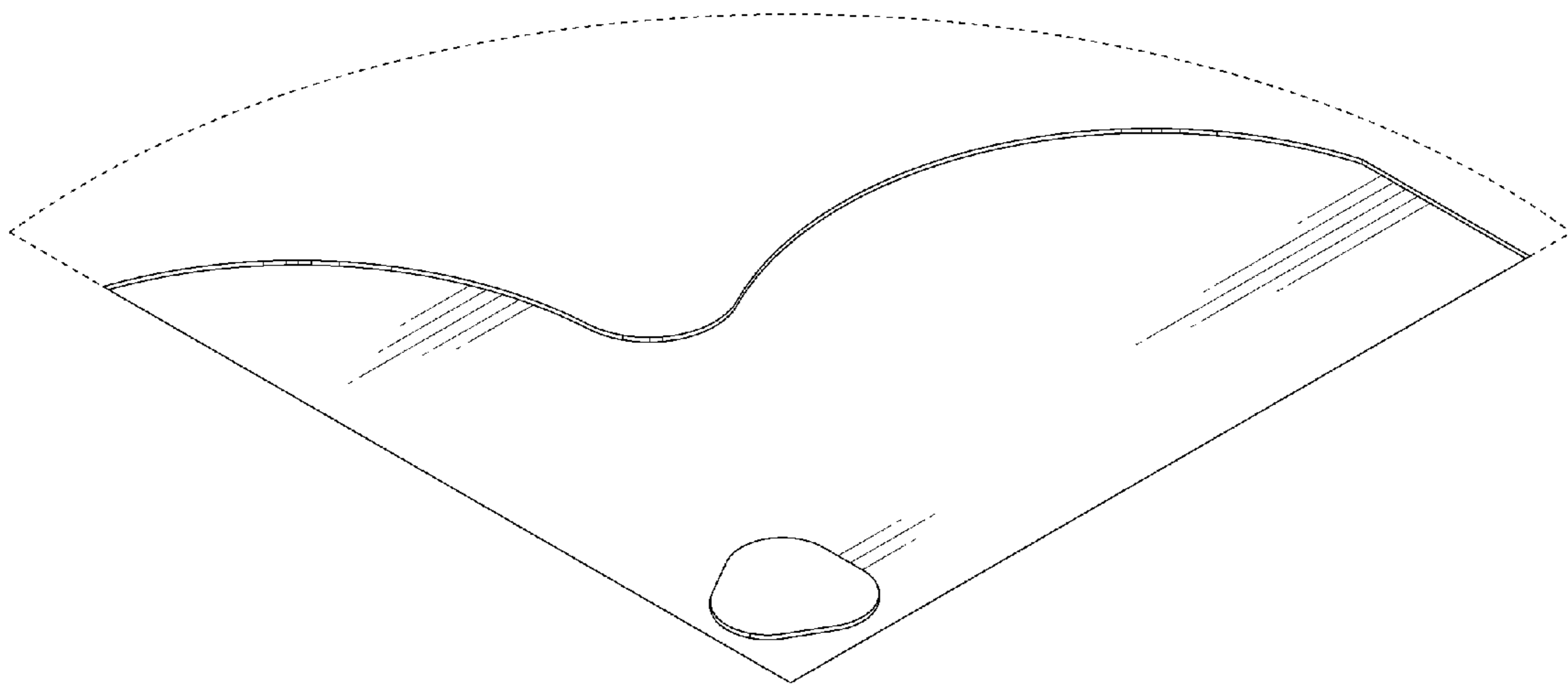


FIG. 9

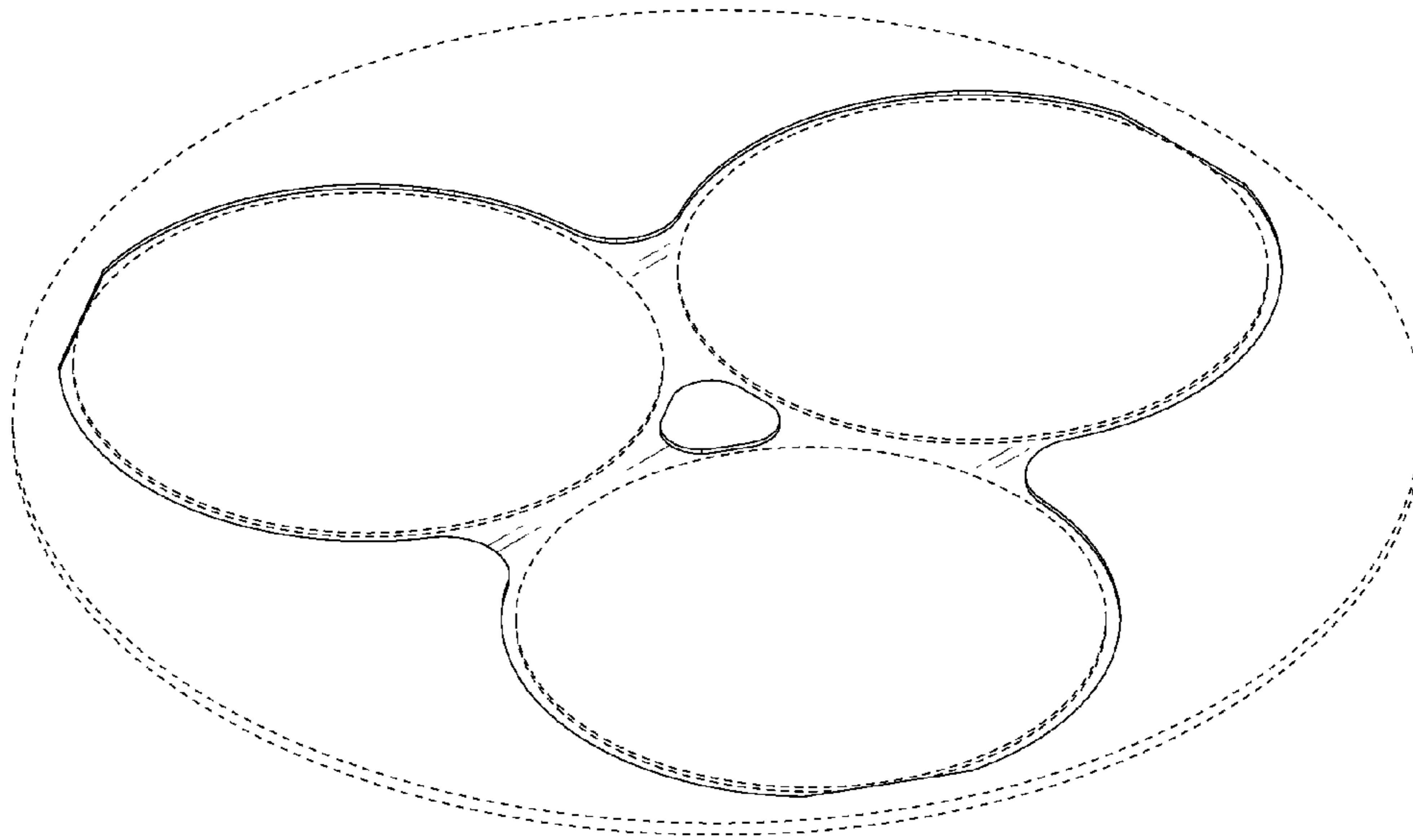


FIG. 10